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Dated: February 1, 2006

Signature: Richard H. Anderson  
(Richard H. Anderson)

Docket No.: 29936/39889  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:

Sang K. Park

Application No.: 10/749,022

Confirmation No.: 9225

Filed: December 30, 2003

Art Unit: 2812

For: METHOD OF FORMING COPPER WIRING IN  
SEMICONDUCTOR DEVICE

Examiner: L. A. Gurley



**(CORRECTIVE) AMENDMENT IN RESPONSE TO**

**NOTICE OF NON-COMPLIANT AMENDMENT (37 CFR 1.121)**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated July 13, 2005 and the Notice of Non-Compliant Amendment dated January 27, 2006, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.